

WST3400

N-Ch MOSFET

General Description

The WST3400 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3400 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

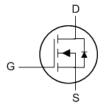
BVDSS	RDSON	ID
30V	18mΩ	7A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-23-3L Pin Configuration





		Ra	Rating	
Symbol	Parameter	10s	Steady State	Units
V _{DS}	Drain-Source Voltage		30	
V _{GS}	Gate-Source Voltage	1	±12	
I _D @T₀=25℃	Continuous Drain Current, V _{GS} @ 10V ¹		7.0	А
I _D @T _c =70℃	Continuous Drain Current, V_{GS} @ $10V^1$ 6.9 6.0		6.0	А
I _{DM}	Pulsed Drain Current ²		25	
P₀@T _A =25℃	Total Power Dissipation ³ 1.3		1	W
P _D @T _A =70℃	Total Power Dissipation ³	0.84	0.64	W
T _{STG}	Storage Temperature Range	-55	-55 to 150	
TJ	Operating Junction Temperature Range	-55	-55 to 150	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹		125	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		95	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		80	°C/W

Absolute Maximum Ratings



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Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.025		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =5A		18	28	mΩ
R _{DS(ON)}		V _{GS} =2.5V , I _D =4A		24	38	
V _{GS(th)}	Gate Threshold Voltage		0.5	0.8	1.2	V
	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, I _D =250uA		-4.8		mV/℃
	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25℃			1	uA
I _{DSS}		V _{DS} =24V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm12V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		7		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.5	5	Ω
Qg	Total Gate Charge (4.5V)			6	8.4	
Q _{gs}	Gate-Source Charge			2.5	3.5	nC
Q _{gd}	Gate-Drain Charge			2.1	2.9	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V , V _{GS} =10V , R _G =3.3Ω I _D =5A		2.4	4.8	
Tr	Rise Time			7.8	14	
T _{d(off)}	Turn-Off Delay Time			22	44	ns
T _f	Fall Time			4	8	
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		572	800	
Coss	Output Capacitance			81	112	pF
C _{rss}	Reverse Transfer Capacitance			65	91	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}				2	А
I _{SM}	Pulsed Source Current ^{2,4}	$V_G = V_D = 0V$, Force Current			25	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.2	V
t _{rr}	Reverse Recovery Time			19		nS
Q _{rr}	Reverse Recovery Charge	IF=5A , dI/dt=100A/ μs , T _J =25 $^\circ C$		1.04		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3.The power dissipation is limited by 150 $^\circ\!\!\mathbb{C}$ $\,$ junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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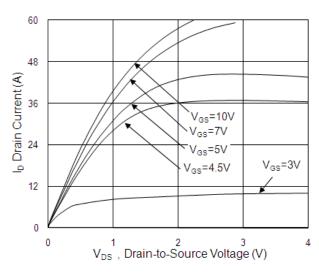


Fig.1 Typical Output Characteristics

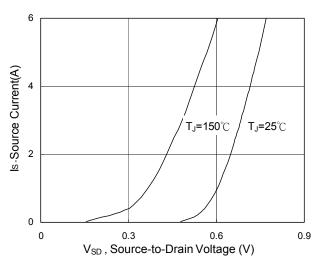


Fig.3 Forward Characteristics Of Reverse

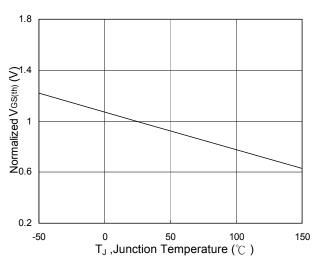


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

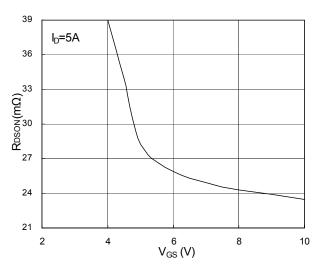


Fig.2 On-Resistance vs. Gate-Source

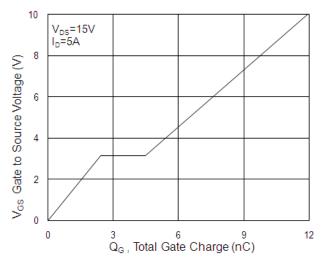


Fig.4 Gate-Charge Characteristics

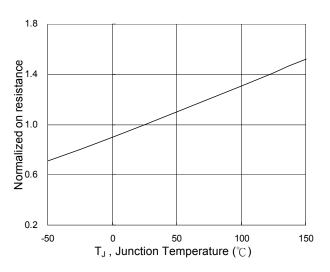


Fig.6 Normalized R_{DSON} vs. T_{J}

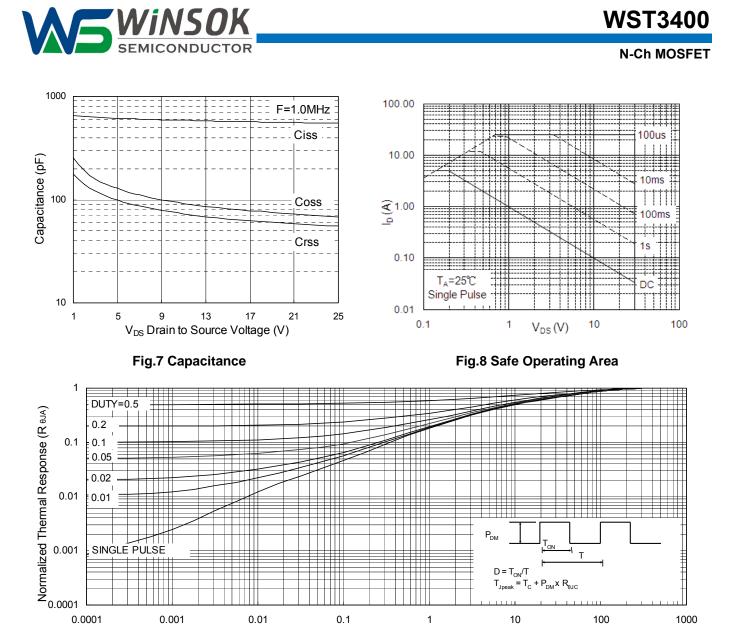
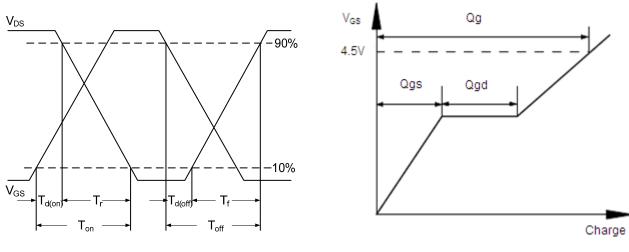


Fig.9 Normalized Maximum Transient Thermal Impedance

t, Pulse Width (s)



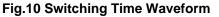


Fig.11 Gate Charge Waveform



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